

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	1935	"257"/\$.ccls. and (substrate board wafer chip die ic) same align\$4 adj3 (mark element) and (dielectric insulat\$3) same (metal conduct\$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/25 13:36
L4	155	"361"/\$.ccls. and (substrate board wafer chip die ic) same align\$4 adj3 (mark element) and (dielectric insulat\$3) same (metal conduct\$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/25 13:43
L5	1253	"438"/\$.ccls. and (substrate board wafer chip die ic) same align\$4 adj3 (mark element) and (dielectric insulat\$3) same (metal conduct\$3)	US-PGPUB; USPAT; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/25 13:43